

In the Claims:

Please amend claims 1-10 and add new claim 11 pursuant to 37 CFR 1.121(c)(1)(i) as set forth in the "clean" version set forth below. Entry is respectfully requested. A version with markings to show the changes made pursuant to 37 CFR 1.121(c)(ii) is attached hereto as Appendix A.

SUB
C1
B4

Claim 1. (Amended) A mounting structure of a printed circuit board for establishing electrical connection to a semiconductor package, said mounting structure comprising:

a pad formed on a first surface of said printed circuit board;

a connection wiring formed on a second surface opposite to said first surface;

and

a via formed through said printed circuit board, said via providing electrical communication between said pad and said connection wiring.

Claim 2. (Amended) A mounting structure as in claim 1, wherein said via has an annular shape on said printed circuit board for establishing said electrical communication.

SUB
C1
B4

Claim 3. (Twice Amended) A mounting structure as in claim 1, wherein a plating is provided on the surface of said pad and an inner surface of said via.

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B6

Claim 4. (Amended) A mounting structure as in claim 1, wherein said via is formed in said pad of said printed circuit board corresponding to a corner of said semiconductor package.

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C1
B7

Claim 5. (Twice Amended) A mounting structure as in claim 1, wherein said via has a truncated cone shape for providing said electrical communication.

Sub
C1
B8

Claim 6. (Amended) A mounting structure as in claim 3, wherein said via has a truncated cone shape for providing said electrical communication.

B8

Claim 7. (Amended) A mounting structure as in claim 2, wherein a space is provided between an outer circumference of said pad and a solder resist on said printed circuit board.

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B9

Claim 8. (Amended) A mounting structure as in claim 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

Claim 9. (Amended) A mounting structure as in claim 2, wherein said via has a truncated cone shape for providing said electrical communication.

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cont
B9

Claim 10. (Amended) A mounting structure as in claim 8, wherein said via has a truncated cone shape for providing said electrical communication.

SUB
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Claim 11. (New) A mounting structure of a semiconductor package in which a semiconductor package is mounted by soldering on a pad of a printed circuit board for electrical connection with a connection wiring, characterized in that

B10

a via is formed through an entire thickness of said printed circuit board,

said pad is integrated with said via on one surface of said printed circuit board,

said pad and said semiconductor package are connected to said via on one surface of said printed circuit board by penetrating a pair into said via or by soldering, and

said connection wiring is connected to said via on the other surface of said printed circuit board.
